

**HYSOL GR900**
(LMC20572-Q1L4)

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PRODUCT DESCRIPTION

HYSOL GR900 provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Filler Type	Spherical silica
Filler Weight, %	89±1
Filler cut	75µm
Typical Package(s)	QFN,DFN
Product Benefits	<ul style="list-style-type: none">● Halogen free● High adhesion● Low moisture absorption● High reliability● Good electrical performance

HYSOL GR900 is a green molding compound designed for QFN.

HYSOL GR900 meets UL 94 V-0 Flammability at 1/8 inch thickness.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Property	Typical Value
Spiral Flow, @ 175°C, inches	49
Gel Time @ 175°C, seconds	36
Shelf Life @ 5°C, days	183
Specific Gravity, g/cm ³	2.02

TYPICAL PROCESS DATA

Handling	Typical Value
Preheat Temperature, convection mold, °C	70 to 90
Molding Temperature, °C	170 to 185
Molding Pressure, Kg/cm ²	40 to 85
Transfer Time, seconds	7 to 15
Curing Time, seconds	90 to 150
Post Cure Time, hours	4 to 8

HYSOL GR900 has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements taken at **175°C** unless otherwise noted. All physical, electrical and analytical measurements taken on specimens cured for **2 minutes @ 175°C** with post cure of 6 hours @ **175°C**, unless otherwise specified.

Physical Properties Property**Typical Value**

Glass Transition Temperature (T _g), °C	124
Coefficient of Thermal Expansion, ppm/°C:	
Below T _g	7
Above T _g	23
Flexural Modulus @ 25°C, N/mm ²	22600
Flexural Strength @ 25°C, N/mm ²	148
Moisture Absorption, 24 hours PCT, %	0.2

Application Specific Properties

Thermal Conductivity, W/(m-K)	0.9
Volume resistivity @ 21°C, 500 V, Ω-cm	50×10 ¹⁵

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5°C. Storage greater than 5°C can adversely affect product properties. Material removed from containers may be contaminated during use. Do not return products to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Electronics Co., Ltd. Technical Service Center or Customer Service Representative.

NOTE

This product is a developmental product. It is not now, and may not be in the future, commercially available. The properties of the uncured material and the physical properties of the cured material have been established as a point of reference only. The information provided in this Lab Data Sheet (LDS) including the recommendations for use and application of the product are based on our best knowledge and experience of the product as at the date of this LDS. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

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